

MATERIAL DECLARATION SHEET

Package Type	PTVS1-190C-TH			
Product Line	Semiconductor products			
Compliance Date	10 June 2019			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.06855	Bisphenol Copolymer	25036-25-3	60	2.8471	4.7452
				Alumina Trihydrate	21645-51-2	15	0.7118	
				Fused Silica	60676-86-0	20	0.949	
				Hydrated Iron Oxide	20344-49-4	1.5	0.0712	
				Titanium Dioxide	13463-67-7	1.5	0.0712	
				Melamine Cyanurate	37640-57-6	1.5	0.0712	
				Amine Adduct	Trade Secret	0.5	0.0237	
2	Electrodes	Copper Alloy	0.8225	Copper	7440-50-8	99.1	56.423	56.9354
				Silver	7440-22-4	0.4	0.2277	
				Misc, not to declare	-	0.5	0.2847	
3	Terminations	Copper Alloy	0.25077	Copper	7440-50-8	99.5	17.2721	17.3589
				Misc. not to declare	-	0.5	0.0868	
4	Chip	Silicon	0.06055	Silicon	7440-21-3	85.34	3.577	4.1914
				Aluminum	7429-90-5	5.13	0.215	
				Nickel	7440-02-0	9.09	0.381	
				Gold	7440-57-5	0.44	0.0184	
5	Die Attach	Solder	0.18625	Lead	7439-92-1	92.5	11.9257	12.8926
				Tin	7440-31-5	5	0.6446	
				Silver	7440-22-4	2.5	0.3223	
6	Die Coating	Silicone	0.056	Polysiloxane	63148-62-9	22.11	0.8571	3.8765
				Chromium Sesquioxide	1308-38-9	5.67	0.2198	

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				Fumed Silica	112945-52-5	11.11	0.4307		
				Filler	Trade Secret	61.11	2.3689		
		Total Weight:	1.44462						

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)